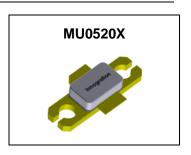
200W, HF-200MHz 28V High Power RF LDMOS

Description

The MU0520X is a 200W single ended 28V LDMOS, highly rugged, unmatched for any applications within HF-200MHz

It supports CW, and pulsed and any modulated signal at either saturated or linear application.



• Typical Performance (On Innogration multiple fixtures with device soldered):

 $V_{DD} = 28 \text{ Volts}$, $I_{DQ} = 150 \text{ mA}$, CW.

Frequency	Pin (dBm)	Gp (dB)	P _{OUT} (W)	η _D (%)	2 nd (dB)	3 rd (dB)
30MHz	28	25	200	78	-26	-39
40.68MHz	33	20	203	81	-28	-41

Features

- High Efficiency and Linear Gain Operations
- Integrated ESD Protection
- Excellent thermal stability, low HCI drift
- Large Positive and Negative Gate/Source Voltage Range for Improved Class C Operation
- Pb-free, RoHS-compliant

Suitable Applications

- 2-30MHz (HF or Short wave communication)
- 30-88MHz (Ground communication)
- 54-88MHz (TV VHF I)
- 88-108MHz (FM)
- 118 -140MHz (Avionics)

- 136-174MHz (Commercial ground communication)
- 160-230MHz (TV VHF III)

Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
DrainSource Voltage	$V_{\scriptscriptstyle DSS}$	+95	Vdc
GateSource Voltage	$V_{\sf GS}$	-10 to +10	Vdc
Operating Voltage	V_{DD}	+36	Vdc
Storage Temperature Range	Tstg	-65 to +150	°C
Case Operating Temperature	T _c	+150	°C
Operating Junction Temperature	T,	+225	°C

Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit	
Thermal Resistance, Junction to Case	Do 10	0.55	°C/W	
T _C = 85°C, T _J =200°C, DC test	Rejc	0.55	°C/VV	

Table 3. ESD Protection Characteristics

Test Methodology	Class		
Human Body Model (per JESD22A114)	Class 2		

Table 4. Electrical Characteristics (TA = 25 $^{\circ}$ C unless otherwise noted)

`					
Characteristic	Symbol	Min	Тур	Max	Unit
C Characteristics					
Drain-Source Voltage	$V_{(BR)DSS}$	95			V
V_{GS} =0, I_{DS} =1.0mA	V (BR)DSS	95	· · · · · ·		V
Zero Gate Voltage Drain Leakage Current					^
$(V_{DS} = 75V, V_{GS} = 0 V)$	I _{DSS}			1	μА
Zero Gate Voltage Drain Leakage Current				4	^
$(V_{DS} = 28 \text{ V}, V_{GS} = 0 \text{ V})$	I _{DSS}	·	· · · · · ·	1	μΑ
GateSource Leakage Current				1	^
$(V_{GS} = 10 \text{ V}, V_{DS} = 0 \text{ V})$	I _{GSS}		<u> </u>	ı	μΑ
Gate Threshold Voltage	V (II)		2.2		V
$(V_{DS} = 28V, I_D = 400 \mu A)$	V _{GS} (th)		2.2		V
Gate Quiescent Voltage	V		3.05		V
$(V_{DD} = 28 \text{ V}, I_D = 150 \text{ mA}, \text{Measured in Functional Test})$	$V_{GS(Q)}$				V
Common Source Input Capacitance			187		, r
$(V_{GS} = 0V, V_{DS} = 28 V, f = 1 MHz)$	C _{ISS}		107		pF
Common Source Output Capacitance	6		70		۲
$(V_{GS} = 0V, V_{DS} = 28 V, f = 1 MHz)$	Coss		79		pF
Common Source Feedback Capacitance			4.0		
$(V_{GS} = 0V, V_{DS} = 28 V, f = 1 MHz)$	C_{RSS}		4.6		pF
functional Tests (In Demo Test Fixture, 50 ohm system) $V_{DD} = 28$	3 Vdc, I _{DQ} = 150mA, f	= 150 MHz, Pi	n=2W, CW Sig	gnal Measurem	nents.
Power Gain	Gn		20		dВ

		-	•	
Power Gain	Gp	 20		dB
Drain Efficiency@Pout	η _D	 80		%
Output Power	P _{out}	 200		W
Input Return Loss	IRL	 -7		dB

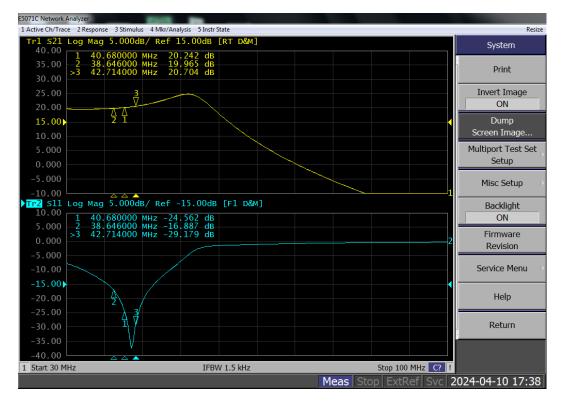
Load Mismatch (In Innogration Test Fixture, 50 ohm system): V_{DD} = 28 Vdc, I_{DQ} = 150 mA, f = 150 MHz

VSWR 20:1 at 200W pulse CW Output Power	No Device Degradation
V3VVK 20.1 at 200VV pulse CVV Output Fower	No Device Degradation

40.68MHz

TYPICAL CHARACTERISTICS

Figure 1: Network analyzer output S11/221



Reference Circuit of Test Fixture Assembly Diagram (PCB file upon request)

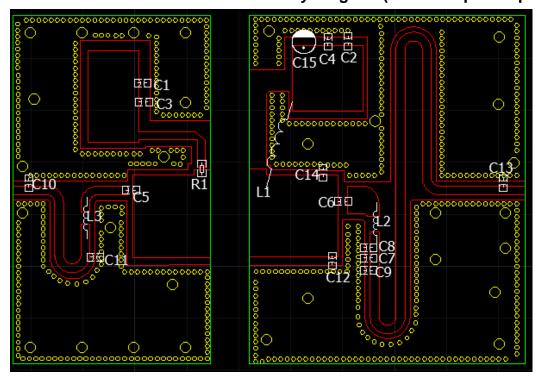


Table 1. Test Circuit Component Designations and Values (40.68MHz)

Component	Description	Suggestion
C1,C2	10uF	10uF/100V
C3~C6	10nF	10nF/100V
C7,C8	150pF	MQ101111
C9	39pF	MQ101111
C10	120pF	MQ101111
C11	47pF	MQ101111
C12	18pF	MQ101111
C13	12pF	MQ101111
C14	200pF	MQ101111
C15	470uF/63V	Electrolytic Capacitor
R1	10 Ω	Chip Resistor
L1	1.5mm/5mm, 8 turns	
L2	1.5mm/5mm, 4 turns	
L3	1.5mm/5mm, 6 turns	
PCB	30Mil	Rogers4350

Package Outline

Flanged ceramic package; 2 leads

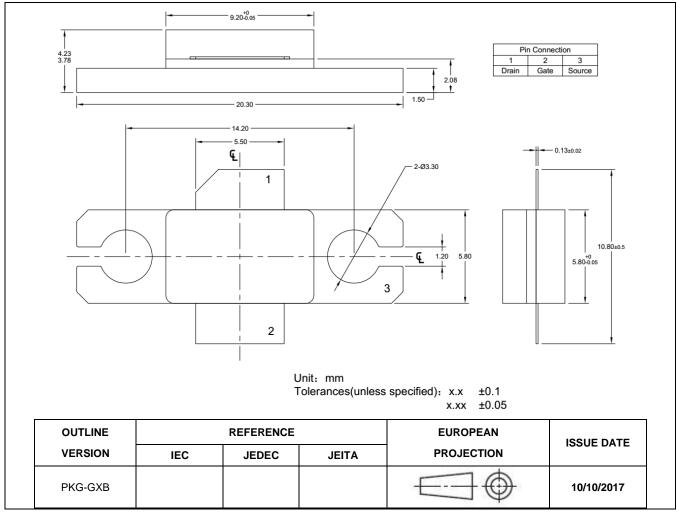


Figure 1. Package Outline PKG-G2E

Revision history

Table 5. Document revision history

Date	Revision	Datasheet Status
2025/4/23	Rev 1.0	Preliminary datasheet

Application data based on TC-24-22/SJJ-25-09

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